Title (en)

TITANIUM ALUMINIDE ALLOY MATERIAL FOR HOT FORGING, FORGING METHOD FOR TITANIUM ALUMINIDE ALLOY MATERIAL, AND FORGED BODY

Title (de)

TITAN-ALUMINID-LEGIERUNGSMATERIAL FÜR WARMSCHMIEDEN, SCHMIEDEVERFAHREN FÜR TITANALUMINID-LEGIERUNGSMATERIAL UND GESCHMIEDETER KÖRPER

Title (fr)

MATÉRIAU D'ALLIAGE D'ALUMINURE DE TITANE POUR FORGEAGE À CHAUD, PROCÉDÉ DE FORGEAGE POUR MATÉRIAU D'ALLIAGE D'ALUMINURE DE TITANE, ET CORPS FORGÉ

Publication

EP 3943627 A4 20221116 (EN)

Application

EP 20773214 A 20200227

Priority

- JP 2019049746 A 20190318
- JP 2020007922 W 20200227

Abstract (en)

[origin: US2021404042A1] A titanium aluminide alloy material for hot forging has a chemical composition including, by atom, aluminum of 43.0% or greater and 45.0% or less, niobium of 4.0% or greater and 6.0% or less, chromium of 1.5% or greater and 3.5% or less, and titanium and an inevitable impurity as a residue.

IPC 8 full level

C22C 14/00 (2006.01); **B21J 5/00** (2006.01); **C22F 1/00** (2006.01); **C22F 1/18** (2006.01)

CPC (source: EP US)

B21J 5/00 (2013.01 - US); **C22C 14/00** (2013.01 - EP US); **C22F 1/183** (2013.01 - EP US)

Citation (search report)

- [XY] JP 3332615 B2 20021007
- [XY] JP H07197154 A 19950801 - MITSUBISHI HEAVY IND LTD
- [Y] DE 102015103422 B3 20160714 - LEISTRITZ TURBINENTECHNIK GMBH [DE]
- [XY] HAN PENG ET AL: "Solidification microstructure characteristics of Ti-44Al-4Nb-2Cr-0.1B alloy under various cooling rates during mushy zone", RARE METALS - XIYOU JINSHU, PRESS OF METALLURGICAL INDUSTRY, BEIJING, CN, vol. 35, no. 1, 27 October 2015 (2015-10-27), pages 35 - 41, XP035720205, ISSN: 1001-0521, [retrieved on 20151027], DOI: 10.1007/S12598-015-0633-Z
- See references of WO 2020189215A1

Designated contracting state (EPC)

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DOCDB simple family (publication)

US 2021404042 A1 20211230; EP 3943627 A1 20220126; EP 3943627 A4 20221116; JP 7233659 B2 20230307; JP WO2020189215 A1 20200924; WO 2020189215 A1 20200924

DOCDB simple family (application)

US 202117447479 A 20210913; EP 20773214 A 20200227; JP 2020007922 W 20200227; JP 2021507142 A 20200227